

AN ELECTRONIC PACKAGE AND METHOD FOR MANUFACTURING AN ELECTRONIC PACKAGE

ABSTRACT

An electronic package is provided. The electronic package comprises a substrate having a first side and a second side, the substrate configured to receive one or more electronic components; a first electronic component mounted to the first side of the substrate; a first mold structure extending over at least part of the first side of the substrate; a group of through-mold connections provided on the first side of the substrate, the through-mold connections substantially formed of non-reflowable electrically conductive material; the first mold structure substantially encapsulating the group of through-mold connections; the group of through-mold connections exposed through the first mold structure. An electronic device comprising such an electronic package is also provided. A method of manufacturing such an electronic package is also provided.

[FIG. 2]